

CRS03

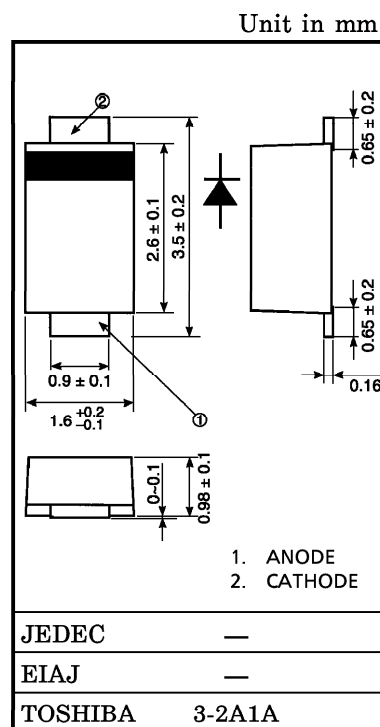
SWITCHING TYPE POWER SUPPLY APPLICATIONS

PORTABLE EQUIPMENT BATTERY APPLICATIONS

- Low Forward Voltage : $V_{FM} = 0.45 \text{ V (Max.)}$
- Average Forward Current : $I_F (AV) = 1.0 \text{ A}$
- Repetitive Peak Reverse Voltage : $V_{RRM} = 30 \text{ V}$

MAXIMUM RATINGS

CHARACTERISTIC	SYMBOL	RATING	UNIT
Repetitive Peak Reverse Voltage	V_{RRM}	30	V
Average Forward Current	$I_F (AV)$	1.0	A
Peak One Cycle Surge Forward Current (Non-Repetitive)	I_{FSM}	20 (50 Hz)	A
Junction Temperature	T_j	-40~125	°C
Storage Temperature Range	T_{stg}	-40~125	°C



Weight : 0.013 g

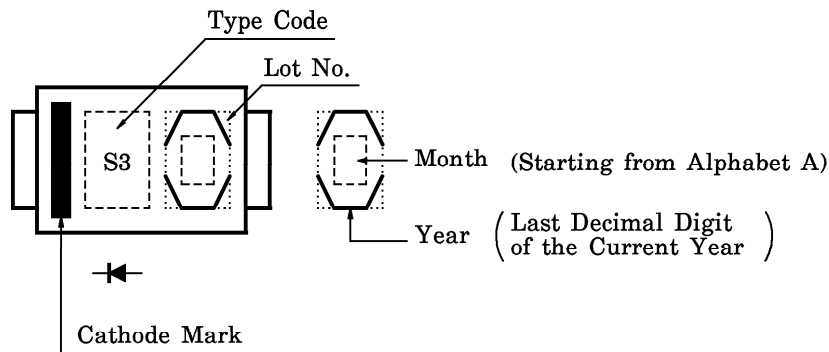
ELECTRICAL CHARACTERISTICS (Ta = 25°C)

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Peak Forward Voltage	$V_{FM} (1)$	$I_{FM} = 0.1 \text{ A}$	—	0.35	—	V
	$V_{FM} (2)$	$I_{FM} = 0.7 \text{ A}$	—	0.425	0.45	V
	$V_{FM} (3)$	$I_{FM} = 1.0 \text{ A}$	—	0.45	—	V
Repetitive Peak Reverse Current	I_{RRM}	$V_{RRM} = 5 \text{ V}$	—	0.5	—	μA
	I_{RRM}	$V_{RRM} = 30 \text{ V}$	—	—	100	μA
Junction Capacitance	C_j	$V_R = 10 \text{ V}, f = 1.0 \text{ MHz}$	—	40	—	pF
Thermal Resistance	$R_{th} (j-a)$	On ceramic substrate	—	—	70	°C / W
		On glass-epoxy substrate	—	—	140	

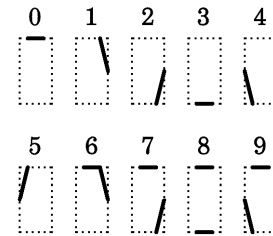
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MARKING



FOLLOWING INDICATES THE DATE OF MANUFACTURE



STANDARD SOLDERING PAD

Unit : mm

